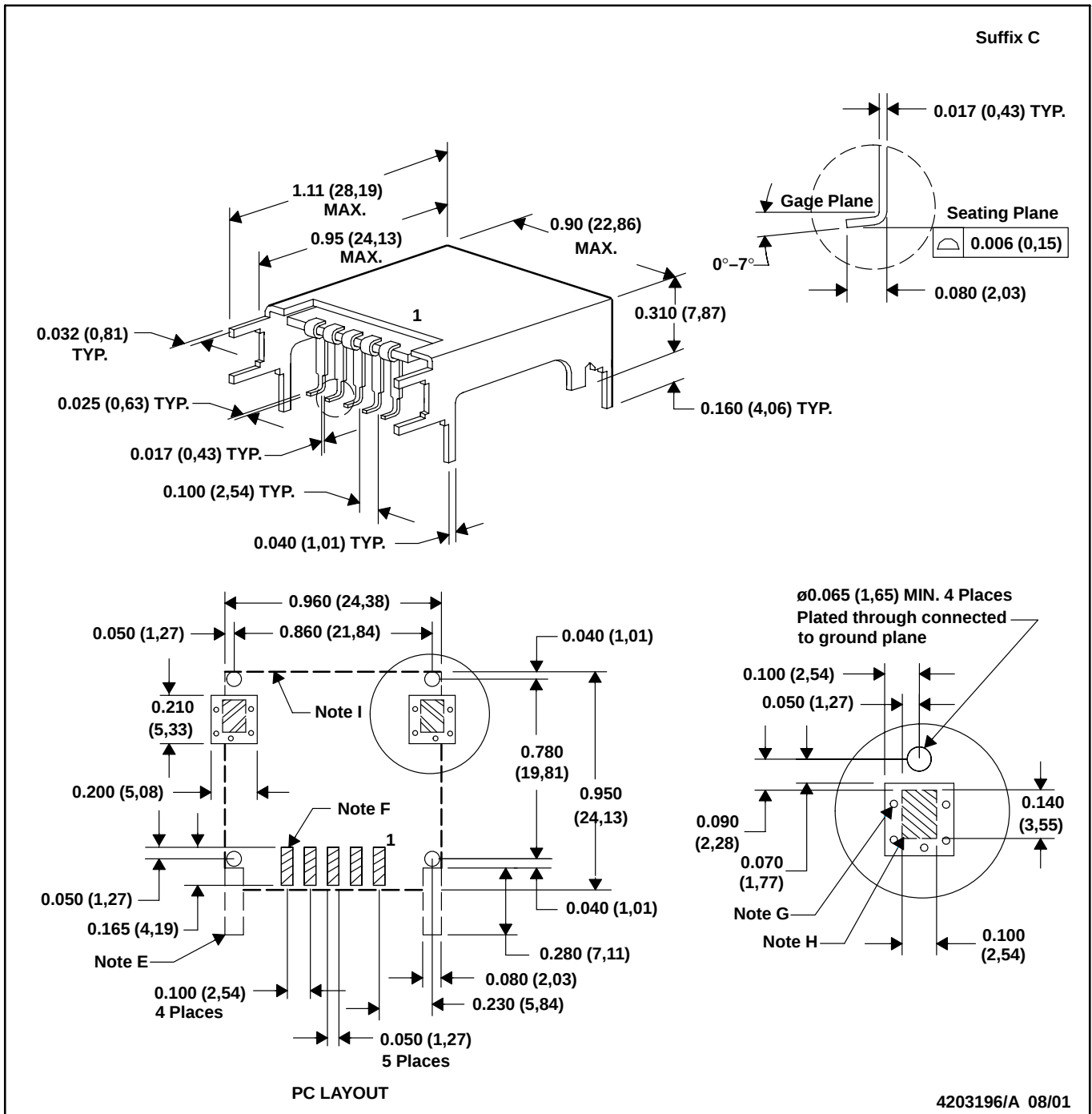


EFM (R-MSIP-G5)

METAL SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 E. Recommended mechanical keep-out area.
 F. Power pin connections should utilize two or more vias per input, ground and output pin.

- G. Vias are recommended to improve copper adhesion.
 H. Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to ground plane.
 I. Case outline reference.

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